

SEMICONDUCTOR PACKAGE

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ABSTRACT OF THE DISCLOSURE

10 A semiconductor package provided with an
interconnection layer including an interconnection
pattern and pad formed on an insulating substrate or
insulating layer, a protective layer covering the
interconnection layer except at the portion of the pad
and the insulating substrate or insulating layer, and an
external connection terminal bonded with the pad exposed
15 from the protective layer, the pad to which the external
connection terminal is bonded being comprised of a
plurality of pad segments, sufficient space being opened
for passing an interconnection between pad segments, and
the pad segments being comprised of at least one pad
20 segment connected to an interconnection and other pad
segments not connected to interconnections.